

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
IPCBoard	1		PMP9792	Any	Printed Circuit Board	
C3, C4, C9, C16, C20, CD1, CD3	7	0.1uF	GRM155R70J104KA01D	MuRata	CAP, CERM, 0.1 μ F, 6.3 V, +/- 10%, X7R, 0402	0402
C10	1	47uF	GRM32ER61C476ME15L	MuRata	CAP, CERM, 47 μ F, 16 V, +/- 20%, X5R, 1210	1210
C12, C13	2	1.2pF	GRM1555C1H1R2BA01D	MuRata	CAP, CERM, 1.2 pF, 50 V, +/- 8.3%, C0G/NP0, 0402	0402
C14	1	12pF	GRM1555C1H120JA01D	MuRata	CAP, CERM, 12 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
C17, C18	2	12pF	GRM1555C1E120JA01D	MuRata	CAP, CERM, 12 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
C19	1	1uF	GRM155R61A105KE15D	MuRata	CAP, CERM, 1 μ F, 10 V, +/- 10%, X5R, 0402	0402
CD2, CD4, CD5	3	4.7uF	GRM155R61C475ME11D	MuRata	CAP, CERM, 4.7 μ F, 16 V, +/- 20%, X5R, 0402	0402
CIN, Cout1	2	10uF	GRM155R60J106ME11	MuRata	CAP, CERM, 10 μ F, 6.3 V, +/- 20%, X5R, 0402	0402
Cout2	1	22uF	GRM21BR61E226ME44L	MuRata	CAP, CERM, 22 μ F, 25 V, +/- 20%, X5R, 0805	0805
E1	1		ANTENNA_DN007A	N/A	2.4GHz PCB Antenna. There is nothing to buy or mount.	SMD, 3-Leads
J1	1		TSW-106-07-G-S	Samtec	Header, 100mil, 6x1, Gold, TH	6x1 Header
J2	1		47346-1001	Molex	Receptacle, Micro-USB Type B, 0.65 mm, 5x1, R/A, Bottom Mount SMT	Receptacle, 0.65mm, 5x1, R/A, SMT
J3, J4, J5, J6, J7	5		TSW-103-07-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	3x1 Header
J11	1		GRPBO52VWQS-RC	Sullins Connector Solutions	Header, 1.27mm, 5x2, Gold, SMT	Header, 1.27mm, 5x2, SMT
L1	1	2.2uH	1285AS-H-2R2M	Toko	Inductor, Shielded, Metal Composite, 2.2 μ H, 1.2 A, 0.204 ohm, SMD	1.6x2mm
L2	1	10uH	VLS201612ET-100M	TDK	Inductor, Shielded, Ferrite, 10 μ H, 0.47 A, 1.026 ohm, SMD	2.0x1.20x1.6mm
L12	1	2nH	LQG15HS2N0S02D	MuRata	Inductor, Multilayer, Air Core, 2 nH, 0.3 A, 0.1 ohm, SMD	0402 polarized
L21	1	15nH	LQG15HS15NJ02D	MuRata	Inductor, Multilayer, Air Core, 15 nH, 0.3 A, 0.32 ohm, SMD	0402 polarized
R1	1	845k	CRCW0402845KFKED	Vishay-Dale	RES, 845 k, 1%, 0.063 W, 0402	0402
R2	1	82k	CRCW040282K0JNED	Vishay-Dale	RES, 82 k, 5%, 0.063 W, 0402	0402
R3, R4	2	0	MCR01MZPJ000	Rohm	RES, 0, 5%, 0.063 W, 0402	0402
R6	1	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402
RD1	1	560k	CRCW0402560KJNED	Vishay-Dale	RES, 560 k, 5%, 0.063 W, 0402	0402
S1	1		B3U-1000P	Omron Electronic Components	SWITCH TACTILE SPST-NO 0.05A 12V	3x1.6x2.5mm
S2	1		B3SL-1022P	Omron Electronic Components	SWITCH TACTILE SPST-NO 0.05A 12V	6.2x5.1x6.5mm
U1	1		CC2650F128RSMR	Texas Instruments	Ultra low-power ARM Cortex M3 2.4 GHz Radio MCU, RSM0032B	RSM0032B
Y1	1		FC-135 32.7680KA-A3	Epson	Crystal, 32.768 KHz, 12.5 pF, SMD	SMD, 2-Leads, Body 3.2x1.5mm
Y2	1		TSX-3225 24.0000MF20G-AC3	Epson	Crystal, 24 MHz, 9 pF, SMD	SMD, 4-Leads, Body 2.65x3.35mm, Height 0.6mm
C2	0	2.2uF	GRM155R60J225KE95D	MuRata	CAP, CERM, 2.2 μ F, 6.3 V, +/- 10%, X5R, 0402	0402
C15, C22, C23	0	12pF	GRM1555C1E120JA01D	MuRata	CAP, CERM, 12 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
Cout12	0	10uF	GRM155R60J106ME11	MuRata	CAP, CERM, 10 μ F, 6.3 V, +/- 20%, X5R, 0402	0402
Cout22	0	22uF	GRM21BR61E226ME44L	MuRata	CAP, CERM, 22 μ F, 25 V, +/- 20%, X5R, 0805	0805
FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
FL1	0	1500 ohm	BLM18HE152SN1D	MuRata	Ferrite Bead, 1500 ohm @ 100 MHz, 0.5 A, 0603	0603
H1, H2, H3, H4	0		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
H5, H6, H7, H8	0		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
J8, J9, J10	0		TSW-102-07-G-S	Samtec	Header, 100mil, 2x1, Gold, TH	2x1 Header
J12	0		SMA-10V21-TGG	Hus-Tsan Group Co., Ltd.	Connector, SMA, Vertical, Gold, SMD	SMD, 4-Leads, Body 7.1x7.1mm
R5	0	0	MCR01MZPJ000	Rohm	RES, 0, 5%, 0.063 W, 0402	0402
U2	1		TPS62770YFPR	Texas Instruments	TPS62770YFP, YFP0016ACAC	YFP0016ACAC

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
U6	1		DD-12864WE-4A	Densitron Displays	OLED Display, SMD	OLED Module, 31.26x26.7mm

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